

Optical Components

Rev. 4 [Mar. 2009]

OL6204N-80-AP10

1625nm \pm 10nm 80mW Pulsed MQW Laser Diode DIL Module with SMF

1. DESCRIPTION

OL6204N-80-AP10 is a 1625nm Laser Diode in DIL package with SMF.

2. FEATURES

- Fiber output: Po=80mW
- Pulsed MQW FP Laser
- 14-pin DIL package module
- Single mode fiber (SMF)
- Built-in TEC
- RoHS compliant

3. APPLICATION

- OTDRs
- Optical measuring instruments

4. OPTICAL AND ELECTRICAL CHARACTERISTICS

(TLD=25°C, 10 μ s Pulse width and 1% Duty, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Threshold Current	I _{th}	---	---	25	50	mA
Operation Current	I _{op}	Pf=80mW	---	500	800	mA
LD Forward Voltage	V _{fl}		---	2.0	4.0	V
Center Wavelength	λ_c		1615	1625	1635	nm
Spectral Width	σ	Pf=80mW, RMS \times 1	---	---	10	nm
Rise Time	τ_r	I _{bias} =I _{th} Pf=1mW, 10-90%	---	---	1	ns
Fall Time	τ_f		---	---	1	ns
Cooler Capacity	ΔT	Pf=80mW	40	---	---	°C
Cooler Current	I _c	$\Delta T=40^\circ\text{C}$, Pf=80mW	---	---	1	A
Cooler Voltage	V _c	$\Delta T=40^\circ\text{C}$, Pf=80mW	---	---	2	V
Thermistor Resistance	R _{th}	$\Delta T=40^\circ\text{C}$, Pf=80mW	9.5	10	10.5	k Ω

5.ABSOLUTE MAXIMUM RATING

(Tcase = 25°C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Fiber Output Power	Pf	96*	mW
LD Reverse Voltage	Vrl	2.0	V
LD Forward Current	Ifl	800*	mA
Cooler Current	Ic	1.2	A
Operating Temperature	Topr	-20 to +65	°C
Storage Temperature	Tstg	-40 to +70	°C

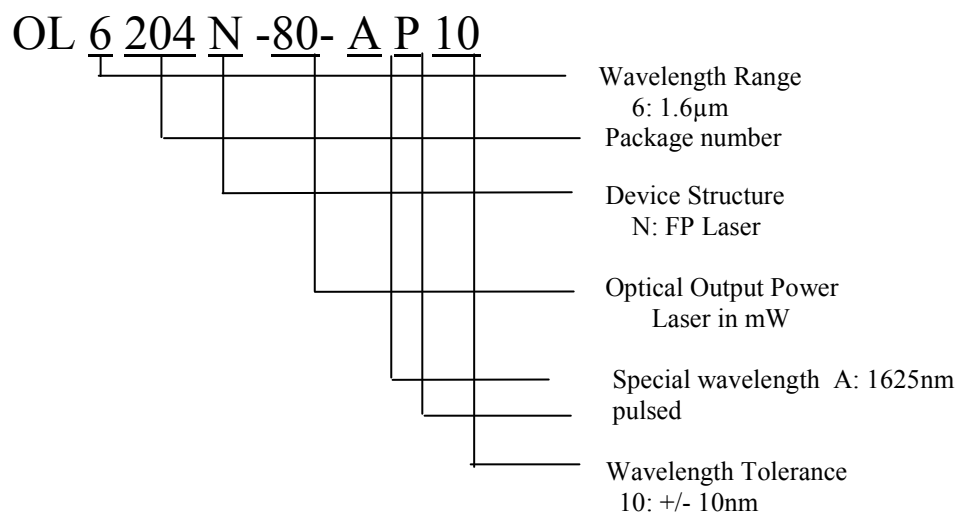
* Pulse width ≤ 10μs , duty ≤ 1%

Exceeding these ratings may lead to immediate destruction or permanent deterioration of the device.

6. CONNECTOR AND FIBER SPECIFICATIONS

Parameter	Specifications	Unit
Type	SMF	---
Mode Field Diameter	10±1	μm
Cladding Diameter	125±2	μm
Jacket Diameter	900	μm
Length	1 (Min.)	m
Connector	FC/SPC	---

7. ORDERING INFORMATION



8.ATTACHED DATA (at 25°C)

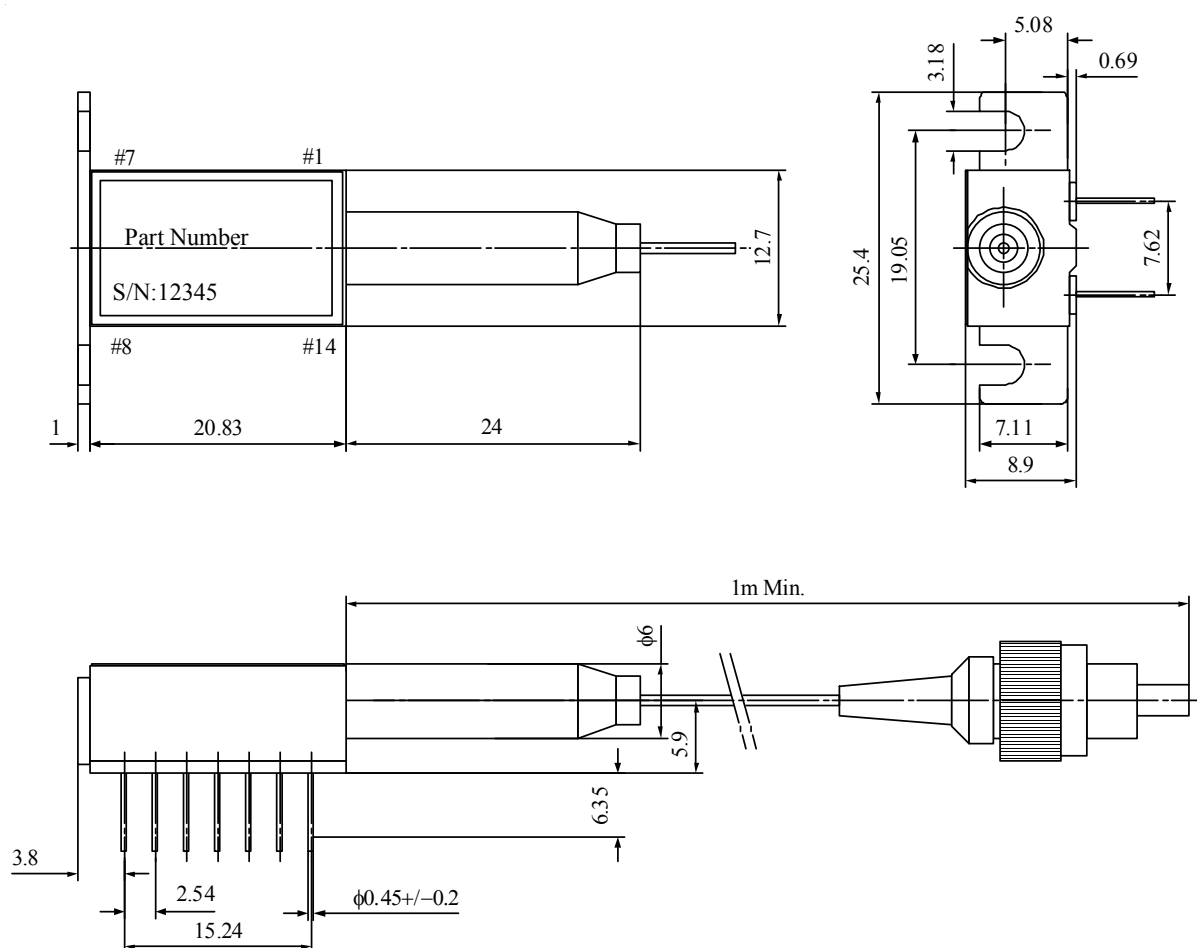
- (1) If-Pf graph (2) Spectrum graph at Pf=80mW
- (3) Threshold current (Ith) (4) Operating current (Iop) at Pf=80mW
- (5) Center wavelength(λc) at Pf=80mW (6) Spectral Width(σ) at Pf=80mW

9.Outline Drawing

All dimensions in millimeters

Tolerances unless noted +/-0.5

Package No. 204(Unit: mm)

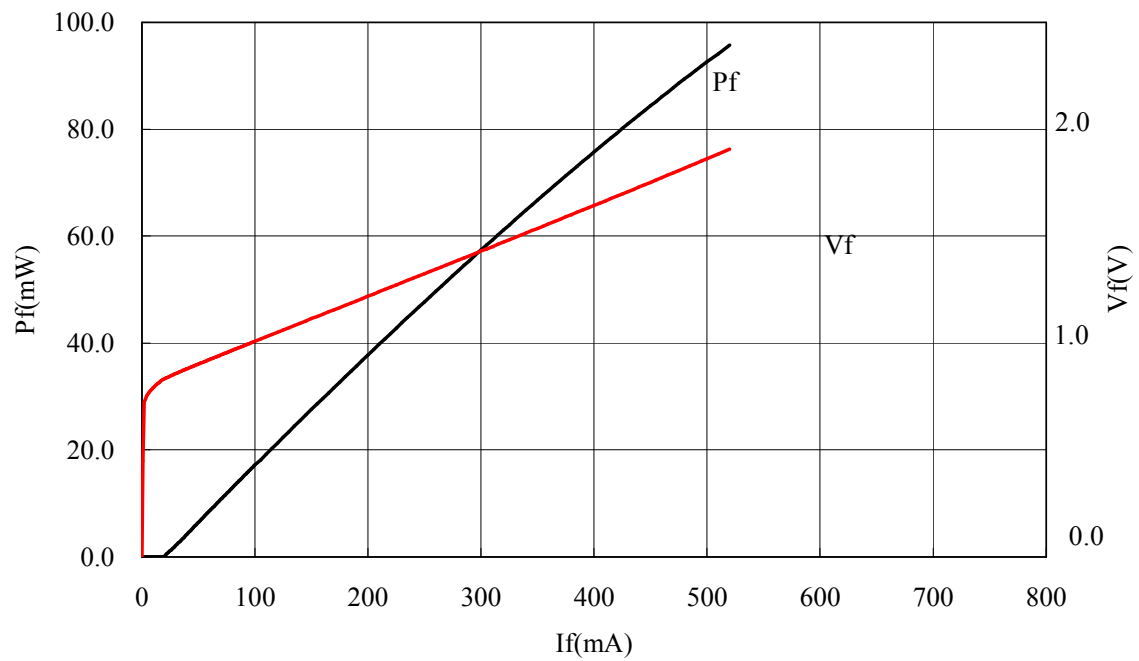


Package Pinout

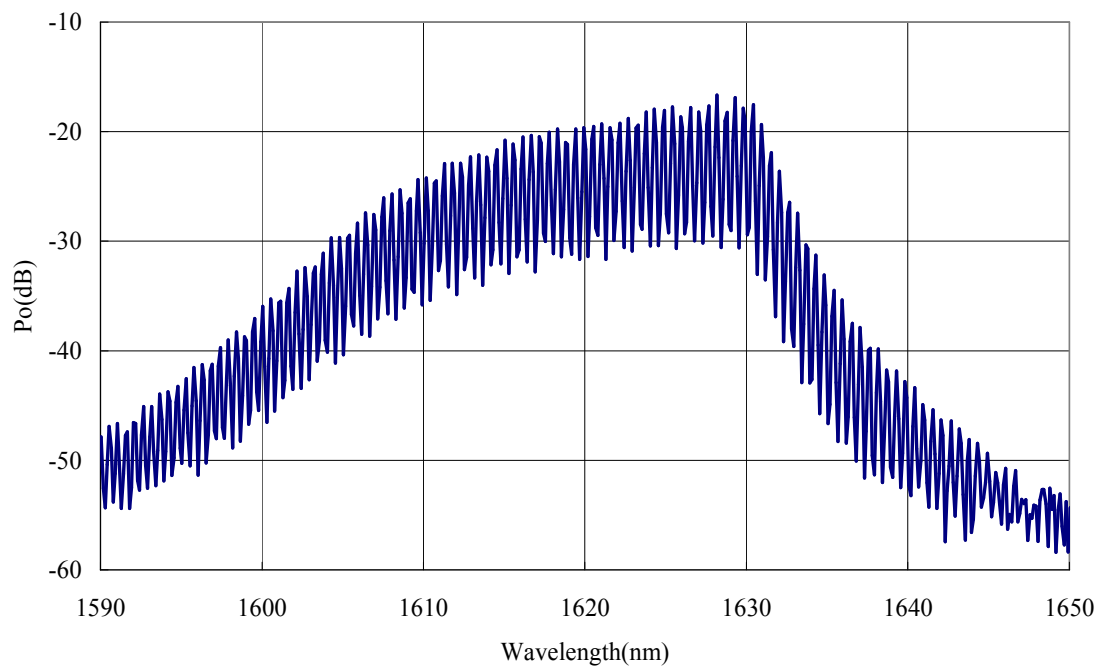
Pin No.	Function	Pin No.	Function
1	TEC+	8	NC
2	NC	9	LD Cathode
3	NC	10	GND
4	NC	11	Thermistor
5	LD Anode(GND)	12	Thermistor
6	NC	13	NC
7	NC	14	TEC-

10.TYPICAL OPERATING CHARACTERISTICS

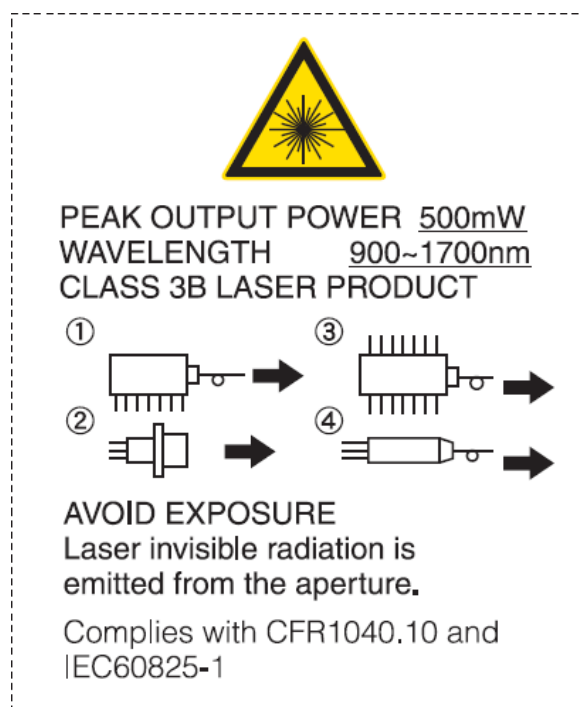
Optical and Electrical Characteristics



Spectrum Graph



SAFETY INFORMATION ON THIS PRODUCT



Warning Laser Beam	<p>A laser beam is emitted from this laser diode during operation. The invisible or visible laser beam, directly or indirectly, may cause injury to the eye or loss of eyesight.</p> <p>Do not look directly into the laser beam.</p> <p>Avoid exposure to the laser beam, any reflected or collimated beam.</p>
Caution GaAs Product	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled, ingested or swallowed.</p> <p>Do not destroy or burn the product.</p> <p>Do not crush or chemically dissolve the product.</p> <p>Do not put the product in the mouth.</p> <p>Observe related laws and company regulations when discarding this product. The product should be excluded from general industrial waste or household garbage.</p>
Caution Optical Fiber	<p>A glass-fiber is attached on the product. Handle with care.</p> <p>When the fiber is broken or damaged, handle carefully to avoid injury from the damaged part or fragments.</p>

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